MK2 S5E BiCS5 512Gb iTLC - 1/2/4/8D Micro Package PQ Report

October 18,2021

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MK2 S5E BiCS5 512Gb iTLC - 1D 9x13.3x0.87mm Shielded - 315 LGA

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Dimension X-Y-Z, Warpage

1D (shielded)

Item	X(Width)	L(Length)	Package T w/o Bump	Pre-bump Height	Body T w/o Bump	Warpage @ RT
Spec	**9.0+/-0.05mm**	**13.3+/-0.05mm**	**Max. 0.87mm**	**50 +/-20um**	**0.770+/- 0.025mm**	**[-30 um,75um]**
Max	9.012	13.305	0.810	59.1	0.781	28.30
Min	8.968	13.265	0.792	40.3	0.768	9.30
Mean	8.994	13.290	0.800	49.7	0.776	20.27
Std Dev	0.007	0.007	0.005	2.40	0.002	1.8

- Data taken from 60 units from 3 PQ lots (20 units/lot) and all dimensions within spec.

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Wire Bond Data (1D)

	Lot 1		Lot 2		Lot 3	
	Wire Pull	**Ball Shear**	**Wire Pull**	**Ball Shear**	**Wire Pull**	**Ball Shear**
Spec (gf) – Min.	**1.8**	**10**	**1.8**	**10**	**1.8**	**10**
Max (gf)	6.69	23.75	6.51	26.00	6.23	23.92
Min (gf)	5.03	19.05	4.72	19.07	5.01	20.37
Avg (gf)	5.76	21.20	5.57	22.60	5.57	22.13
Std Dev (gf)	0.36	1.12	0.41	2.00	0.61	1.78

- Data taken from 36 wires (5 units/lot) from 3 PQ lots and passed wire pull and bond shear.

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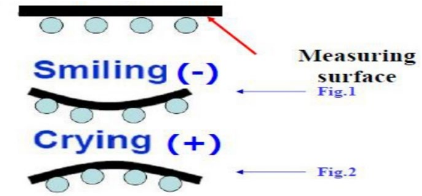
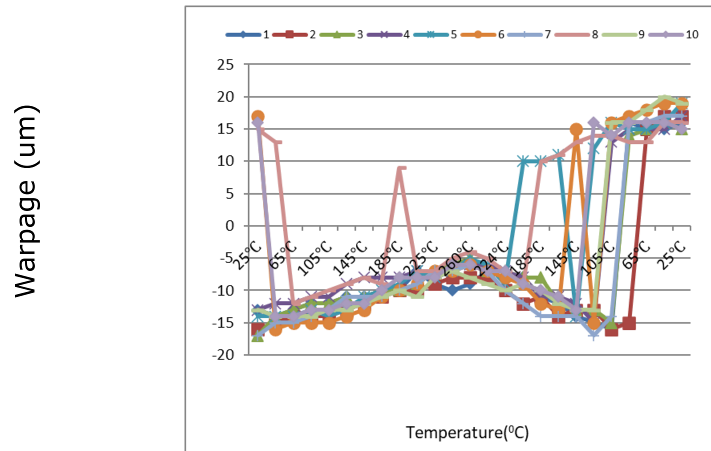
Shadow Moiré (1D)

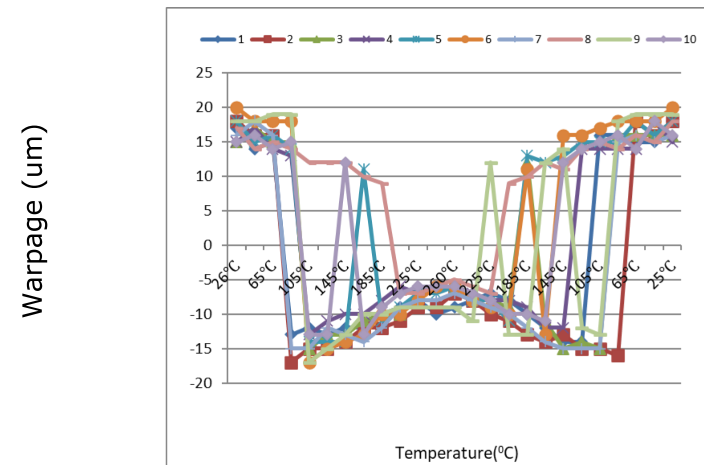


Dry condition samples - meets Apple spec at all specified temp.

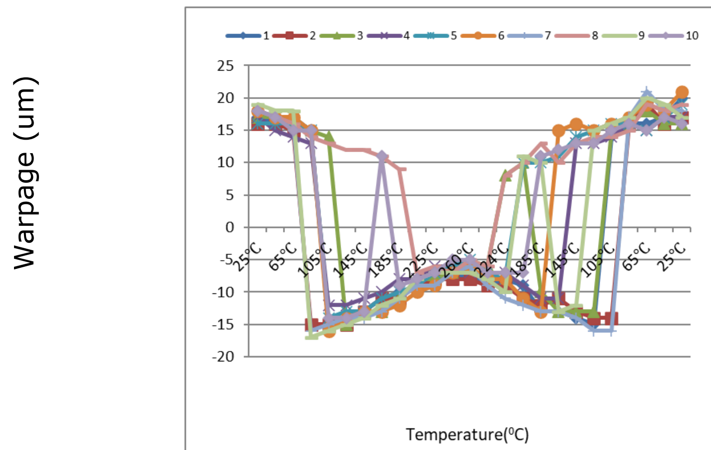
1st reflow



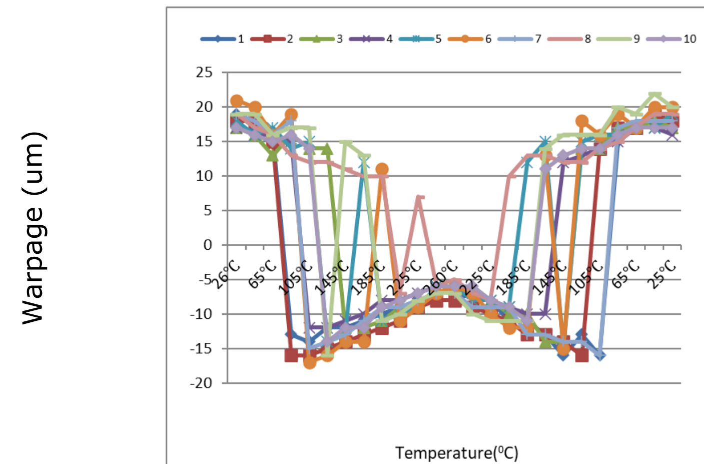
2nd reflow



3rd reflow



4th reflow



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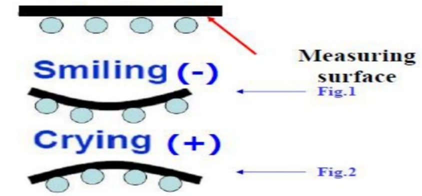
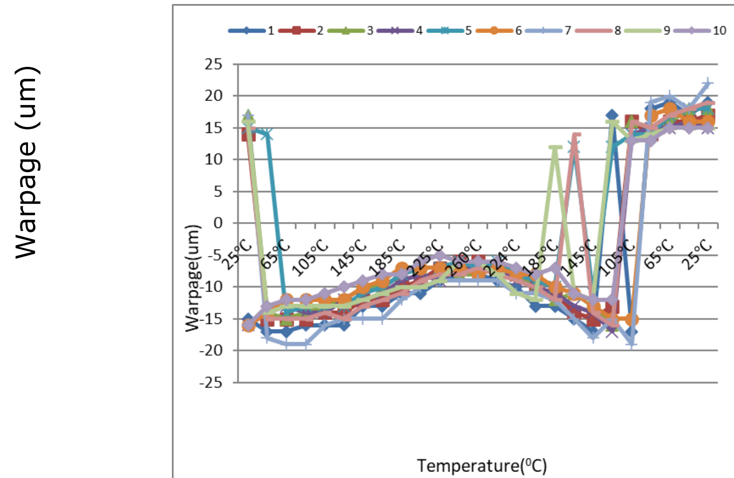
Shadow Moiré (1D)



Wet condition samples - meets Apple spec at all specified temp.

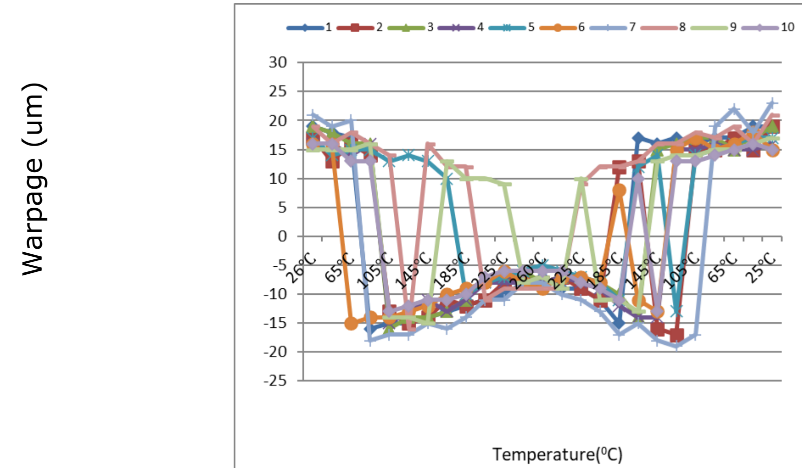
1st reflow

Warpage (um)



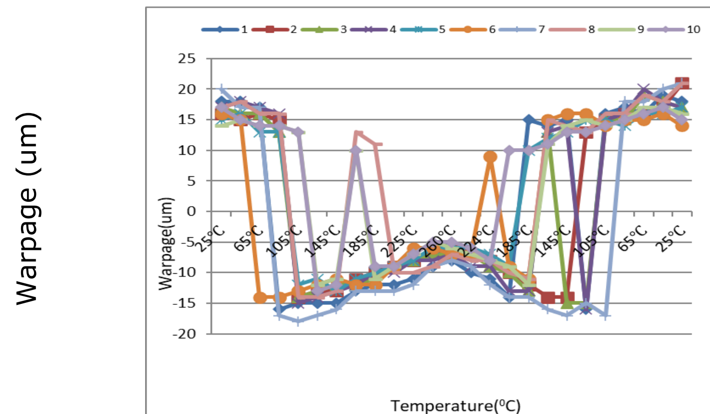
2nd reflow

Warpage (um)



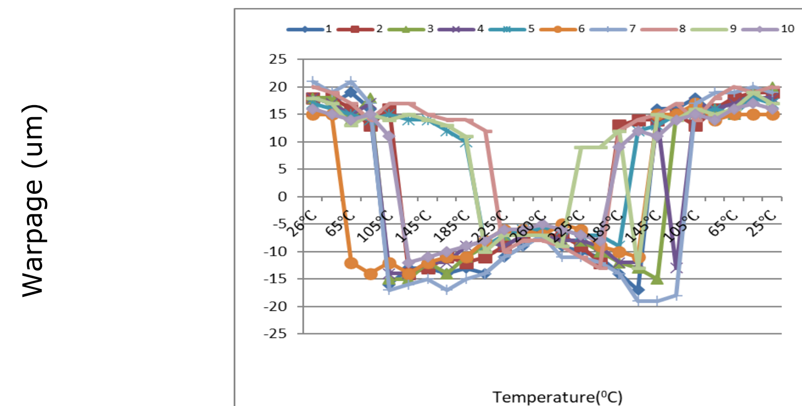
3rd reflow

Warpage (um)



4th reflow

Warpage (um)



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Tape Adhesion Test (1D)

20 units from each of 3 PQ lots

Al No.	Qty	Comment
Lot 1	20	Peeling test pass spec
Lot 2	20	Peeling test pass spec
Lot 3	20	Peeling test pass spec

Tape adhesion test done as per ASTM D-3359 at $T_a = 25°C$ and it meets peeling criterion

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Contact Resistance and Delam check (1D)

Test	Pkg Type	Spec	Test result	Sample size	Remarks
Delamination check by CSAM	Shield	JED22-A113	0 fail / 60ea	60units	Require pre-conditioning with MSL level 3A and measure it after 260C 4x IR reflow
Contact Resistance check	Shield	<0.6Ω	0 fail / 60ea	60 units	

- Data taken from 60 units from 3 PQ lots (20 units/lot).

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Package Reliability Data (1D) – Mini Qual

Package Qual Lot #1 (Substrate Vendor X, EMI-Linco)

Test Items	Sample Size (ea)	Test Condition	Criteria	Intermediate read-point	Result
Pre-condition: MSL3A +4xIR	50	60° C; 60% RH; 40hours 4xIR.	No Failure	SAT result	0/50
				Test result	0/50
TMCL for embedded components after pre-con (Temperature Cycling Test)	25	-55°C to 125°C; 300cycles	No Failure	After 300cys	0/25
Biased-HAST after pre-con (Biased Highly Accelerated Stress Test)	25	110°C, 85%RH; 3.6V/1.95V/0.99V for 96hours.	No Failure	After 96hrs	0/25

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Package Reliability Data (1D) – Mini Qual

Package Qual Lot #2 (Substrate Vendor X, EMI- Tango)

Test Items	Sample Size (ea)	Test Condition	Criteria	Intermediate read-point	Result
Pre-condition: MSL3A +4xIR	50	60° C; 60% RH; 40hours 4xIR.	No Failure	SAT result	0/50
				Test result	0/50
TMCL for embedded components after pre-con (Temperature Cycling Test)	25	-55°C to 125°C; 300cycles	No Failure	After 300cys	0/25
Biased-HAST after pre-con (Biased Highly Accelerated Stress Test)	25	110°C, 85%RH; 3.6V/1.95V/0.99V for 96hours.	No Failure	After 96hrs	0/25

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Package Reliability Data (1D) – Mini Qual

Package Qual Lot #3 (Substrate Vendor Y, EMI-Linco)

Test Items	Sample Size (ea)	Test Condition	Criteria	Intermediate read-point	Result
Pre-condition: MSL3A +4xIR	50	60° C; 60% RH; 40hours 4xIR.	No Failure	SAT result	0/50
				Test result	0/50
TMCL for embedded components after pre-con (Temperature Cycling Test)	25	-55°C to 125°C; 300cycles	No Failure	After 300cys	0/25
Biased-HAST after pre-con (Biased Highly Accelerated Stress Test)	25	110°C, 85%RH; 3.6V/1.95V/0.99V for 96hours.	No Failure	After 96hrs	0/25

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MK2 S5E BiCS5 512Gb iTLC - 2D
9x13.3x0.87mm
Shielded - 315 BGA

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Dimension X-Y-Z, Warpage

2D (shielded)

Item	X(Width)	L(Length)	Package T w/o Bump	Pre-bump Height	Body T w/o Bump	Warpage @ RT
Spec	**9.0+/-0.05mm**	**13.3+/-0.05mm**	**Max. 0.87mm**	**50 +/-20um**	**0.770+/- 0.025mm**	**[-30 um,75um]**
Max	9.009	13.310	0.802	59.8	0.780	25.6
Min	8.968	13.276	0.779	40.5	0.765	9.0
Mean	8.992	13.292	0.787	50.3	0.772	17.0
Std Dev	0.007	0.006	0.004	2.69	0.002	2.82

- Data taken from 60 units from 3 PQ lots (20 units/lot) and all dimensions within spec.

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NAND Wire Bond Data (2D)

	Lot 1		Lot 2		Lot 3	
	Wire Pull	Ball Shear	Wire Pull	Ball Shear	Wire Pull	Ball Shear
Spec (gf) – Min.	**1.8**	**10**	**1.8**	**10**	**1.8**	**10**
Max (gf)	8.32	25.30	8.13	23.99	7.71	23.74
Min (gf)	6.66	19.19	6.23	19.42	6.63	20.01
Avg (gf)	7.43	21.75	7.29	21.74	7.15	21.68
Std Dev (gf)	0.36	0.98	0.38	1.02	0.43	1.32

- Data taken from 36 wires (5 units/lot) from 3 PQ lots and passed wire pull and bond shear.

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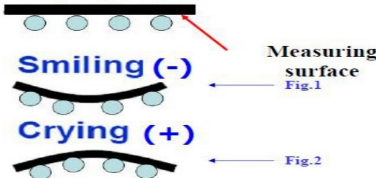
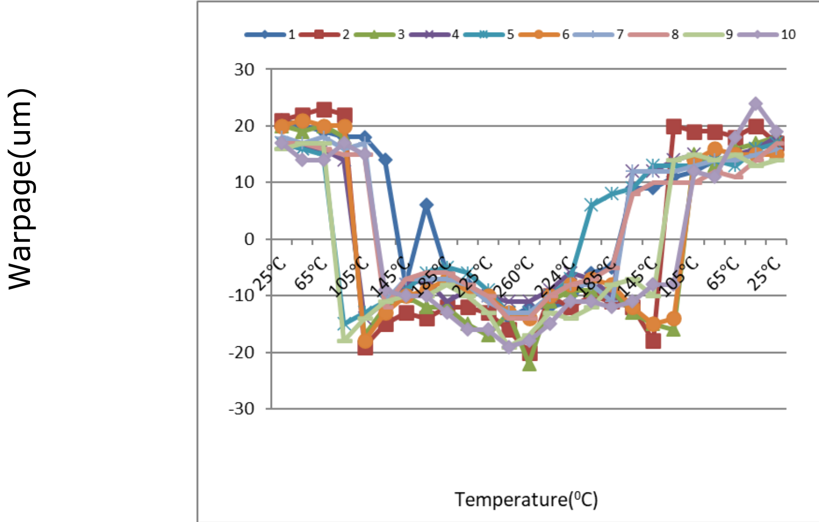
Shadow Moiré (2D)

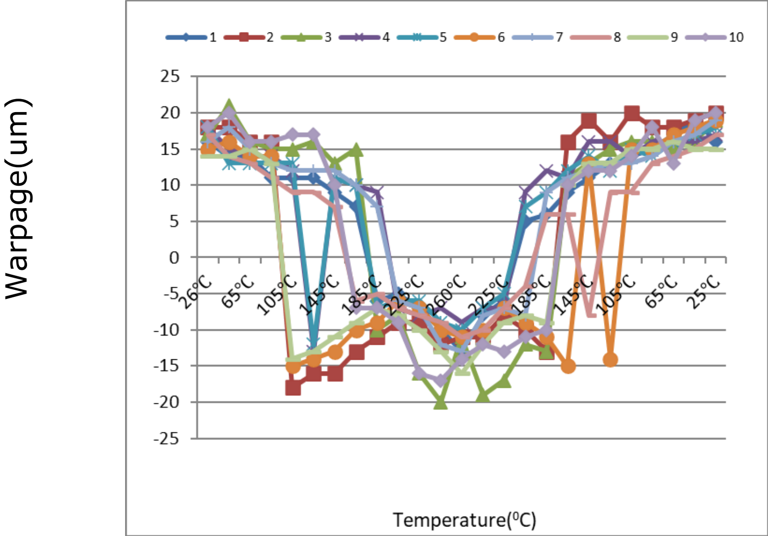
Dry condition samples - meets Apple spec for all temperature range specified



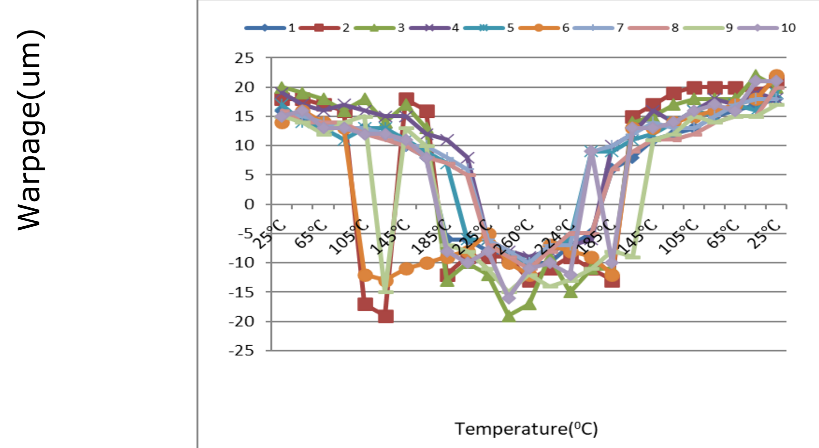
1st reflow



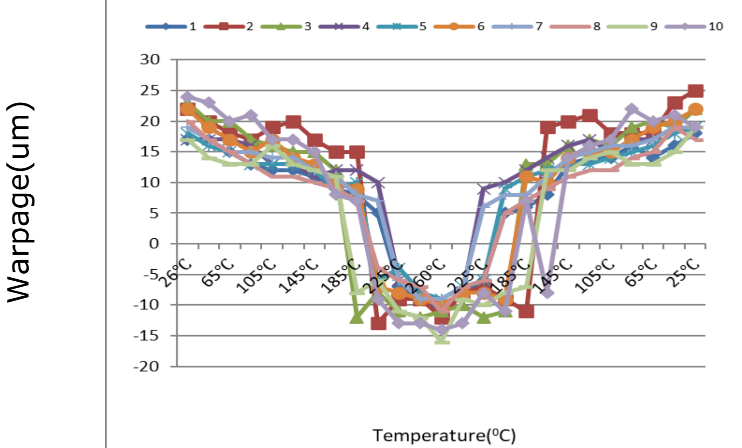
2nd reflow



3rd reflow



4th reflow



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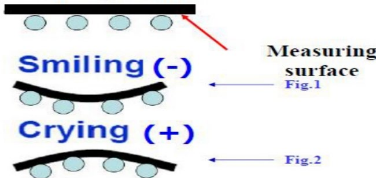
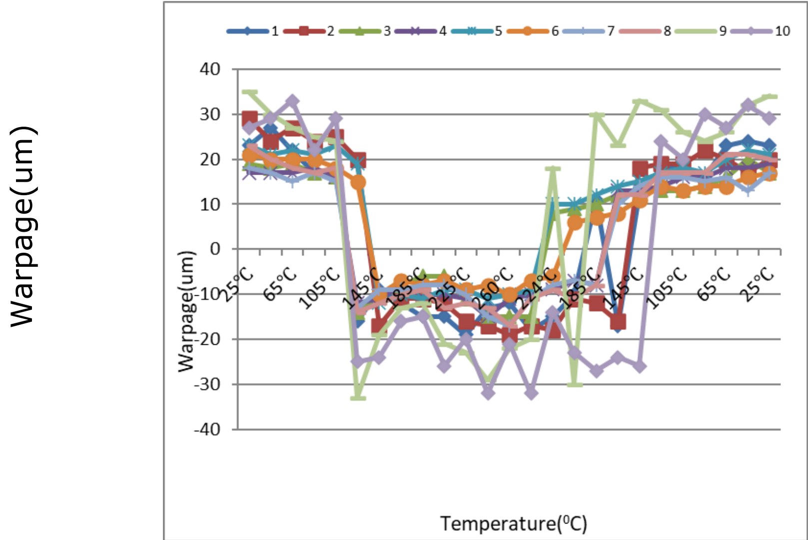
Shadow Moiré (2D)

Wet condition samples - meets Apple spec for all temperature range specified



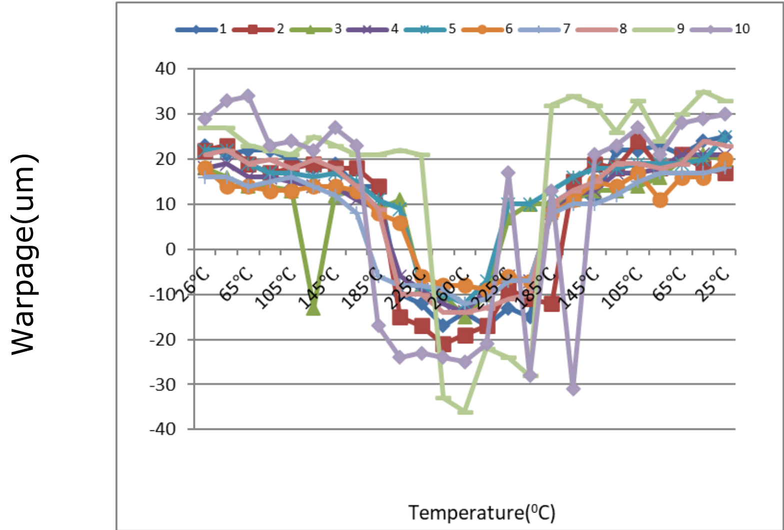
1st reflow

Warpage(um)



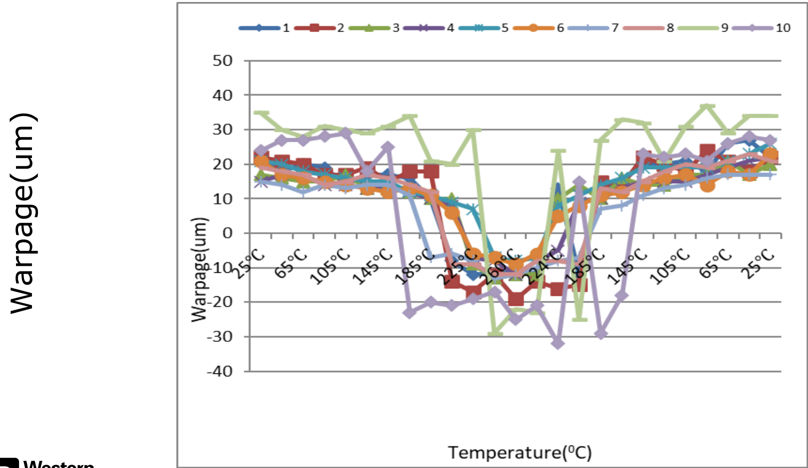
2nd reflow

Warpage(um)



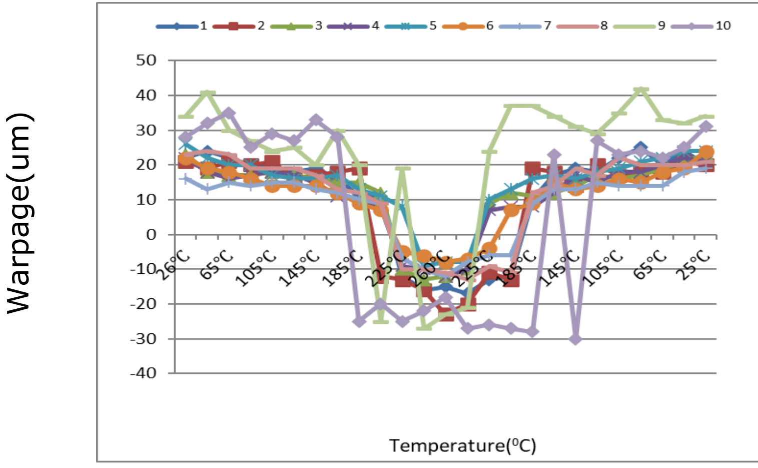
3rd reflow

Warpage(um)



4th reflow

Warpage(um)



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Tape Adhesion test (2D)

20 units from each of 3 PQ lots

Al No.	Qty	Comment
Lot1	20	Peeling test pass spec
Lot2	20	Peeling test pass spec
Lot3	20	Peeling test pass pec

Tape adhesion test done as per ASTM D-3359 at T_a = 25°C and it meets peeling criterion

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Contact Resistance and Delam check (2D)

Test	Pkg Type	Spec	Test result	Sample size	Remarks
Delamination check by CSAM	Shield	JED22-A113	0 fail / 60ea	60units	Require pre-conditioning with MSL level 3A and measure it after 260C 4x IR reflow
Contact Resistance check	Shield	$<0.6\Omega$	0 fail / 60ea	60 units	

- Data taken from 60 units from 3 PQ lots (20 units/lot)

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Package Reliability Data (2D) – Mini Qual

Package Qual Lot #1 (Substrate Vendor Y, EMI-Linco)

Test Items	Sample Size (ea)	Test Condition	Criteria	Intermediate read-point	Result
Pre-condition: MSL3A +4xIR	50	60° C; 60% RH; 40hours 4xIR.	No Failure	SAT result	0/50
				Test result	0/50
TMCL for embedded components after pre-con (Temperature Cycling Test)	25	-55°C to 125°C; 300cycles	No Failure	After 300cys	0/25
Biased-HAST after pre-con (Biased Highly Accelerated Stress Test)	25	110°C, 85%RH; 3.6V/1.95V/0.99V for 96hours.	No Failure	After 96hrs	0/25

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Package Reliability Data (2D) – Mini Qual

Package Qual Lot #2 (Substrate Vendor X, EMI-Tango)

Test Items	Sample Size (ea)	Test Condition	Criteria	Intermediate read-point	Result
Pre-condition: MSL3A +4xIR	50	60° C; 60% RH; 40hours 4xIR.	No Failure	SAT result	0/50
				Test result	0/50
TMCL for embedded components after pre-con (Temperature Cycling Test)	25	-55°C to 125°C; 300cycles	No Failure	After 300cys	0/25
Biased-HAST after pre-con (Biased Highly Accelerated Stress Test)	25	110°C, 85%RH; 3.6V/1.95V/0.99V for 96hours.	No Failure	After 96hrs	0/25

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Package Reliability Data (2D) – Mini Qual

Package Qual Lot #3 (Substrate Vendor Y, EMI-Tango)

Test Items	Sample Size (ea)	Test Condition	Criteria	Intermediate read-point	Result
Pre-condition: MSL3A +4xIR	50	60° C; 60% RH; 40hours 4xIR.	No Failure	SAT result	0/50
				Test result	0/50
TMCL for embedded components after pre-con (Temperature Cycling Test)	25	-55°C to 125°C; 300cycles	No Failure	After 300cys	0/25
Biased-HAST after pre-con (Biased Highly Accelerated Stress Test)	25	110°C, 85%RH; 3.6V/1.95V/0.99V for 96hours.	No Failure	After 96hrs	0/25

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MK2 S5E BiCS5 512Gb iTLC - 4D 9x13.3x0.87mm Shielded - 315 BGA

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Dimension X-Y-Z, Warpage

4D (shielded)

Item	X(Width)	L(Length)	Package T w/o Bump	Pre-bump Height	Body T w/o Bump	Warpage @ RT
Spec	**9.0+/-0.05mm**	**13.3+/-0.05mm**	**Max. 0.87mm**	**50 +/-20um**	**0.770+/-0.025mm**	**[-30 um,75um]**
Max	9.007	13.310	0.833	62.9	0.781	52.7
Min	8.971	13.258	0.797	44.5	0.765	28.6
Mean	8.991	13.28	0.816	52.8	0.772	42.2
Std Dev	0.007	0.007	0.007	2.54	2.67	4.06

- Data taken from 60 units from 3 PQ lots (20 units/lot) and all dimensions within spec.

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NAND Wire Bond Data (4D)

	Lot 1		Lot 2		Lot 3	
	Wire Pull	**Ball Shear**	**Wire Pull**	**Ball Shear**	**Wire Pull**	**Ball Shear**
Spec (gf) – Min.	**1.8**	**10**	**1.8**	**10**	**1.8**	**10**
Max (gf)	6.01	24.77	6.16	23.83	6.85	23.96
Min (gf)	4.04	19.89	5.59	20.86	4.00	19.28
Avg (gf)	4.98	21.95	5.74	22.80	4.92	21.39
Std Dev (gf)	0.53	1.15	0.25	0.76	0.66	0.91

- Data taken from 36 wires (5 units/lot) from 3 PQ lots and passed wire pull and bond shear.

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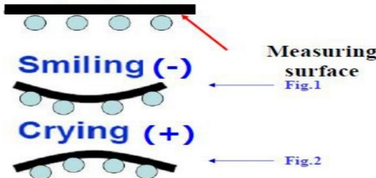
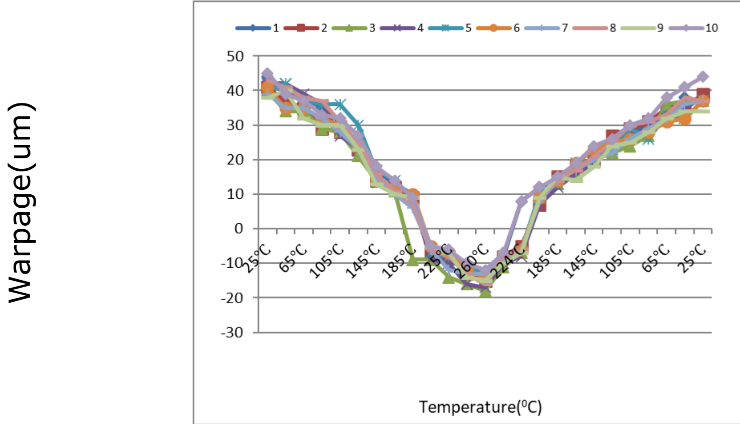
Shadow Moiré (4D)

Dry condition samples - meets Apple spec for all temperature range specified



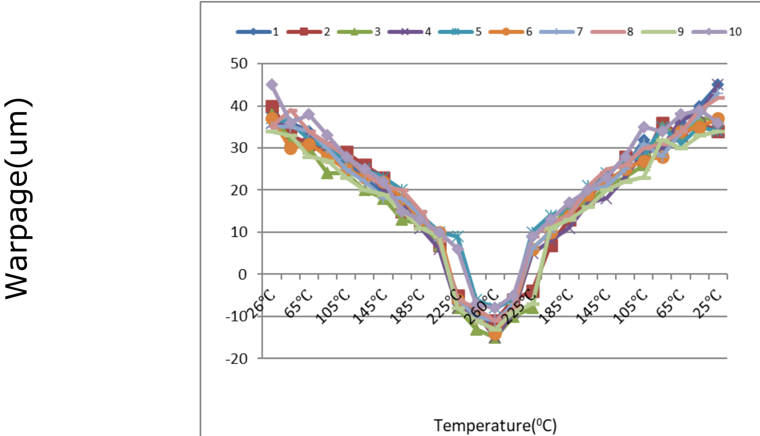
1st reflow

Warpage(um)



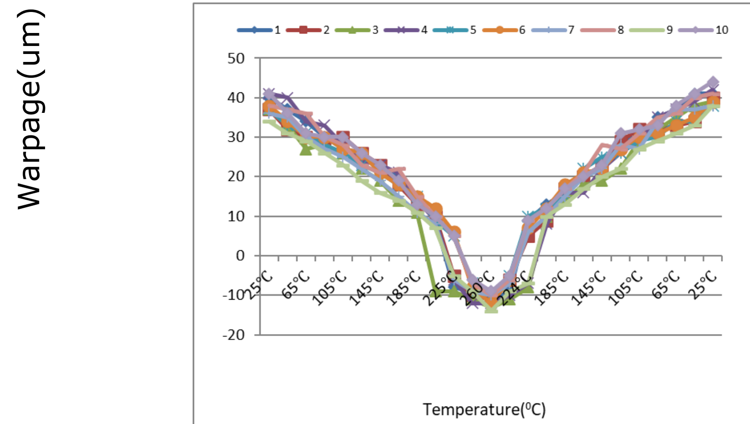
2nd reflow

Warpage(um)



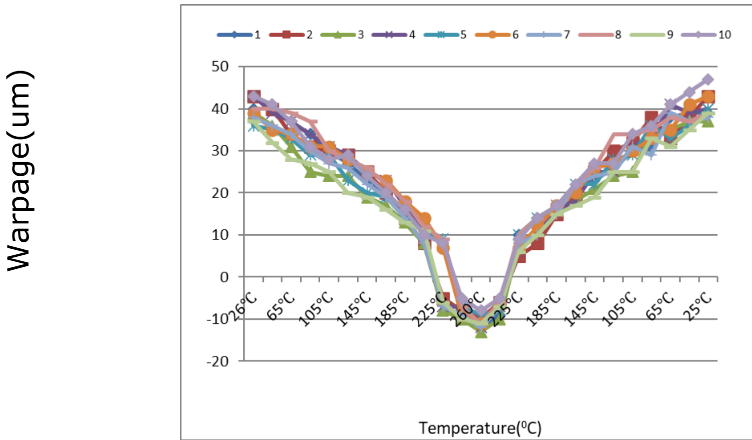
3rd reflow

Warpage(um)



4th reflow

Warpage(um)



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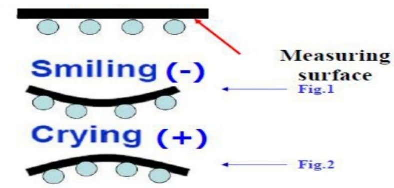
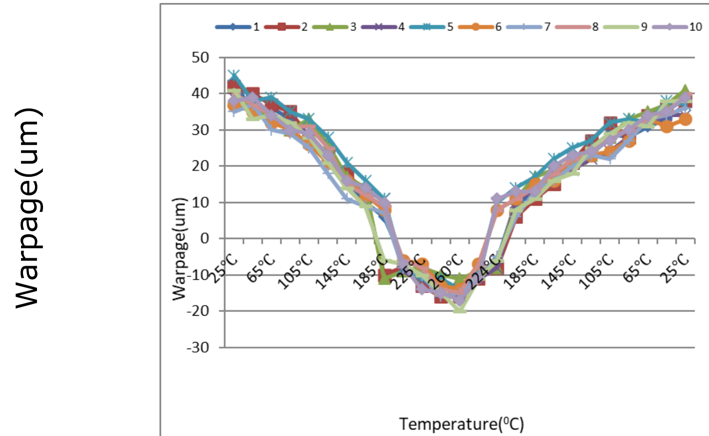
Shadow Moiré (4D)

Wet condition samples - meets Apple spec for all temperature range specified



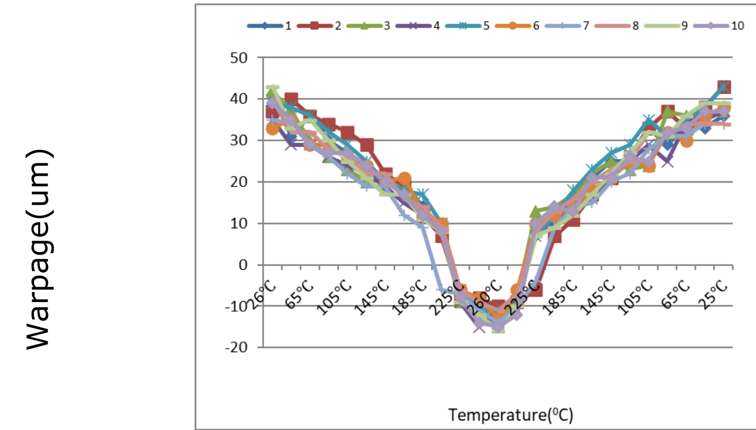
1st reflow

Warpage(um)



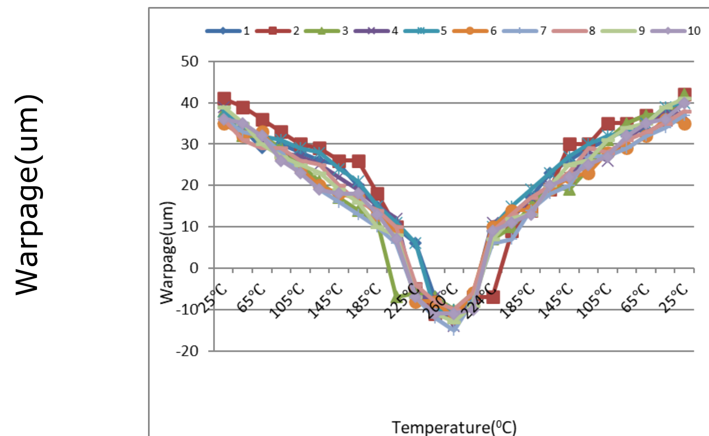
2nd reflow

Warpage(um)



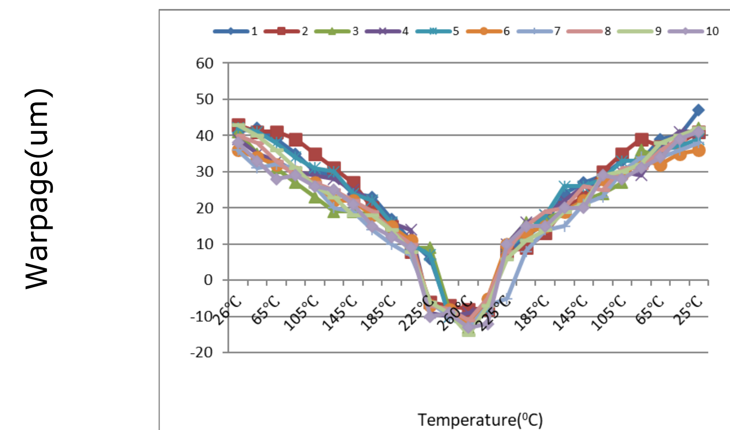
3rd reflow

Warpage(um)



4th reflow

Warpage(um)



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Tape Adhesion test (4D)

20 units from each of 3 PQ lots

AI No.	Qty	Comment
Lot1	20	Peeling test pass spec
Lot2	20	Peeling test pass spec
Lot3	20	Peeling test pass pec

Tape adhesion test done as per ASTM D-3359 at T_a = 25°C and it meets peeling criterion

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Contact Resistance and Delam check (4D)

Test	Pkg Type	Spec	Test result	Sample size	Remarks
Delamination check by CSAM	Shield	JED22-A113	0 fail / 60ea	60units	Require pre-conditioning with MSL level 3A and measure it after 260C 4x IR reflow
Contact Resistance check	Shield	<0.6Ω	0 fail / 60ea	60 units	

- Data taken from 60 units from 3 PQ lots (20 units/lot)

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Package Reliability Data (4D) – Mini Qual

Package Qual Lot #1 (Substrate Vendor Y, EMI-Linco)

Test ItemsC	Sample Size (ea)	Test Condition	Criteria	Intermediate read-point	Result
Pre-condition: MSL3A +4xIR	50	60° C; 60% RH; 40hours 4xIR.	No Failure	SAT result	0/50
				Test result	0/50
TMCL for embedded components after pre-con (Temperature Cycling Test)	25	-55°C to 125°C; 300cycles	No Failure	After 300cys	0/25
Biased-HAST after pre-con (Biased Highly Accelerated Stress Test)	25	110°C, 85%RH; 3.6V/1.95V/0.99V for 96hours.	No Failure	After 96hrs	0/25

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Package Reliability Data (4D) – Mini Qual

Package Qual Lot #2 (Substrate Vendor X, EMI-Tango)

Test ItemsC	Sample Size (ea)	Test Condition	Criteria	Intermediate read-point	Result
Pre-condition: MSL3A +4xIR	50	60° C; 60% RH; 40hours 4xIR.	No Failure	SAT result	0/50
				Test result	0/50
TMCL for embedded components after pre-con (Temperature Cycling Test)	25	-55°C to 125°C; 300cycles	No Failure	After 300cys	0/25
Biased-HAST after pre-con (Biased Highly Accelerated Stress Test)	25	110°C, 85%RH; 3.6V/1.95V/0.99V for 96hours.	No Failure	After 96hrs	0/25

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Package Reliability Data (4D) – Mini Qual

Package Qual Lot #3 (Substrate Vendor X, EMI-Linco)

Test ItemsC	Sample Size (ea)	Test Condition	Criteria	Intermediate read-point	Result
Pre-condition: MSL3A +4xIR	50	60° C; 60% RH; 40hours 4xIR.	No Failure	SAT result	0/50
				Test result	0/50
TMCL for embedded components after pre-con (Temperature Cycling Test)	25	-55°C to 125°C; 300cycles	No Failure	After 300cys	0/25
Biased-HAST after pre-con (Biased Highly Accelerated Stress Test)	25	110°C, 85%RH; 3.6V/1.95V/0.99V for 96hours.	No Failure	After 96hrs	0/25

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MK2 S5E BiCS5 512Gb iTLC - 8D 9x13.3x0.9mm Shielded - 315 BGA

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Dimension X-Y-Z, Warpage

8D (shielded)

Item	X(Width)	L(Length)	Package T w/o Bump	Pre-bump Height	Body T w/o Bump	Warpage @ RT
Spec	**9.0+/-0.05mm**	**13.3+/-0.05mm**	**Max. 0.90mm**	**50 +/-20um**	**0.800+/-0.025mm**	**[-30 um,75um]**
Max	9.024	13.330	0.847	57.7	0.804	45.9
Min	8.978	13.275	0.820	41.6	0.790	20.5
Mean	9.001	13.304	0.836	49.7	0.799	36.2
Std Dev	0.010	0.013	0.005	2.26	0.005	4.75

- Data taken from 60 units from 3 PQ lots (20 units/lot) and all dimensions within spec.

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NAND Wire Bond Data (8D)

	Lot 1		Lot 2		Lot 3	
	Wire Pull	**Ball Shear**	**Wire Pull**	**Ball Shear**	**Wire Pull**	**Ball Shear**
Spec (gf) – Min.	**1.8**	**10**	**1.8**	**10**	**1.8**	**10**
Max (gf)	6.36	23.88	6.55	25.27	5.70	23.83
Min (gf)	4.33	21.59	4.02	20.26	4.29	20.86
Avg (gf)	5.59	23.02	4.92	23.22	5.40	22.80
Std Dev (gf)	0.54	0.59	0.56	0.77	0.46	0.76

- Data taken from 36 wires (5 units/lot) from 3 PQ lots and passed wire pull and bond shear.

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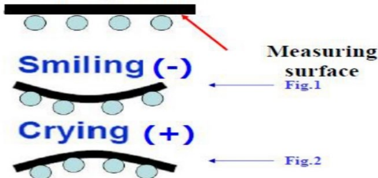
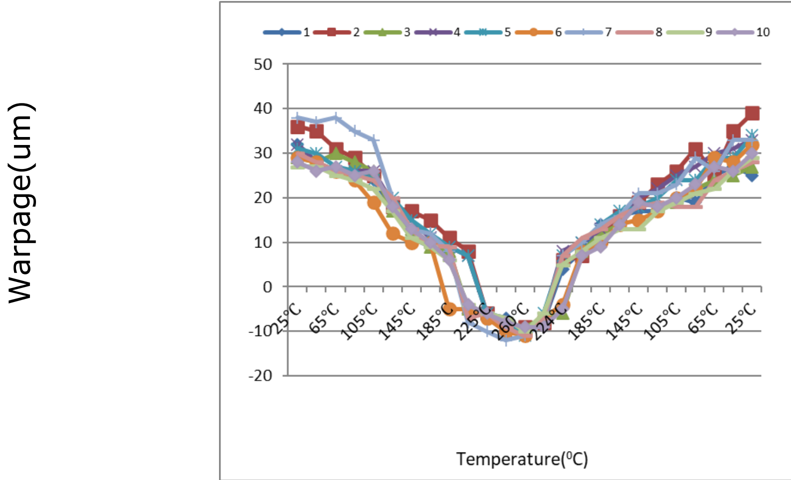
Shadow Moiré (8D)

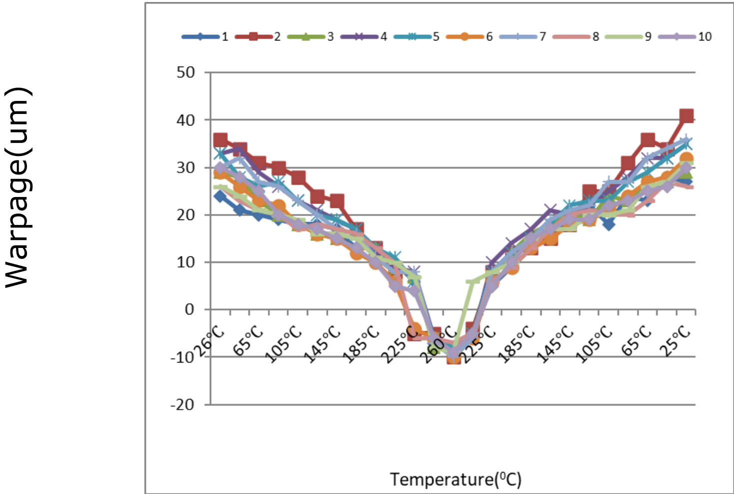
Dry condition samples - meets Apple spec for all temperature range specified



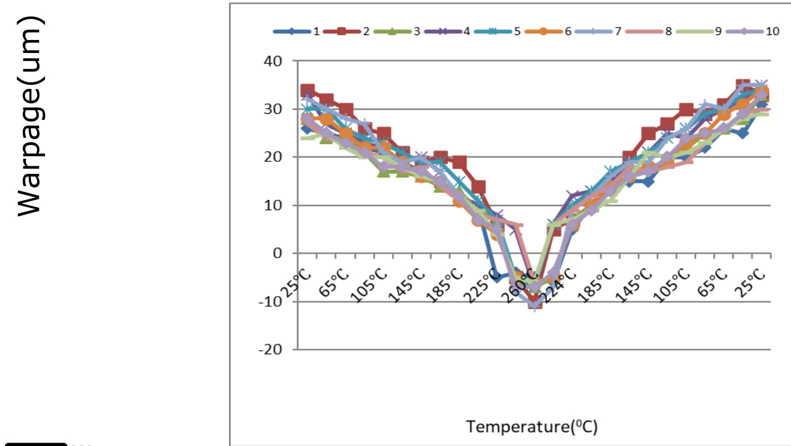
1st reflow



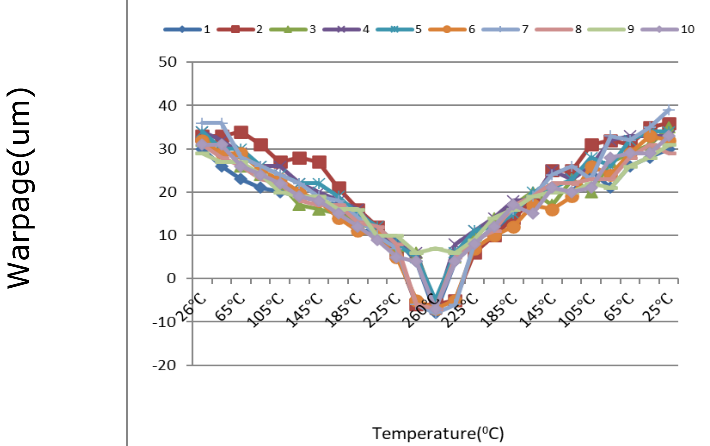
2nd reflow



3rd reflow



4th reflow



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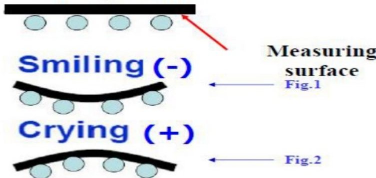
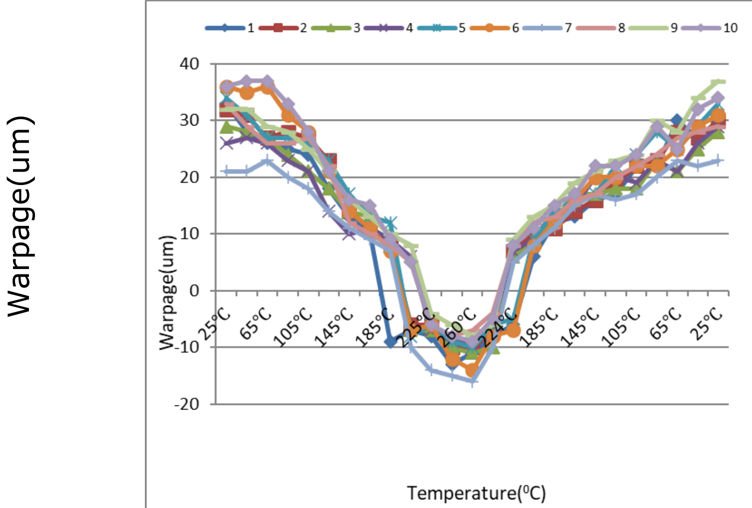
Shadow Moiré (8D)

Wet condition samples - meets Apple spec for all temperature range specified



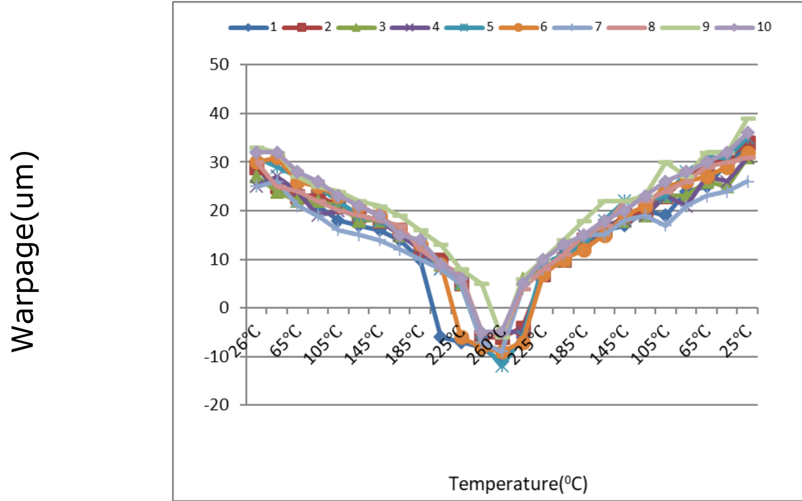
1st reflow

Warpage(um)



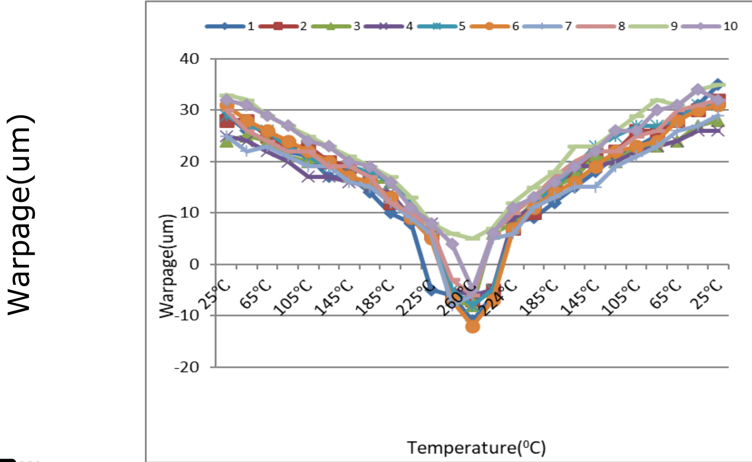
2nd reflow

Warpage(um)



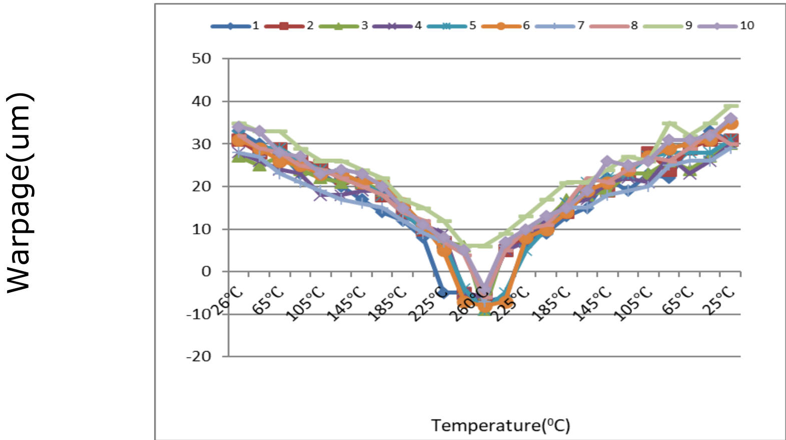
3rd reflow

Warpage(um)



4th reflow

Warpage(um)



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Tape Adhesion test (8D)

20 units from each of 3 PQ lots

AI No.	Qty	Comment
Lot1	20	Peeling test pass spec
Lot2	20	Peeling test pass spec
Lot3	20	Peeling test pass pec

Tape adhesion test done as per ASTM D-3359 at T_a = 25°C and it meets peeling criterion

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Contact Resistance and Delam check (8D)

Test	Pkg Type	Spec	Test result	Sample size	Remarks
Delamination check by CSAM	Shield	JED22-A113	0 fail / 60ea	60units	Require pre-conditioning with MSL level 3A and measure it after 260C 4x IR reflow
Contact Resistance check	Shield	<0.6Ω	0 fail / 60ea	60 units	

- Data taken from 60 units from 3 PQ lots (20 units/lot)

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Package Reliability Data (8D) – Full Qual

Package Qual Lot #1 (Substrate Vendor X, EMI-Linco)

Test Items	Sample Size (ea)	Test Condition	Criteria	Intermediate read-point	Result
Pre-condition: MSL3A +4xIR	280	60° C; 60% RH; 40hours 4xIR.	No Failure	SAT result	0/280
				Test result	0/280
TMCL for embedded components after pre-con (Temperature Cycling Test)	77	-55°C to 125°C; 300cycles	No Failure	After 300cys	0/77
		-55°C to 125°C; 500cycles	No Failure	After 500cys	0/77
		-55°C to 125°C; 700cycles	No Failure	After 700cys	0/77
Biased-HAST after pre-con (Biased Highly Accelerated Stress Test)	77	110°C, 85%RH; 3.6V/1.95V/0.99V for 96hours.	No Failure	After 96hrs	0/77
		110°C, 85% RH; 3.6V/1.95V/0.99V for 264hours.	No Failure	After 264hrs	0/77
Un-Biased-HAST after pre-con (Un-Biased Highly Accelerated Stress Test)	77	110°C, 85%RH; 96hours.	No Failure	After 96hrs	0/77
		110°C, 85% RH; 264hours.	No Failure	After 264hrs	0/77
HTST after pre-con (High Temperature Storage Test)	45	150°C; 300hours	No Failure	After 300hrs	0/45
		150°C; 500hours	No Failure	After 500hrs	0/45

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Package Reliability Data (8D) – Full Qual

Package Qual Lot #2 (Substrate Vendor X, EMI-Tango)

Test Items	Sample Size (ea)	Test Condition	Criteria	Intermediate read-point	Result
Pre-condition: MSL3A +4xIR	280	60° C; 60% RH; 40hours 4xIR.	No Failure	SAT result	0/280
				Test result	0/280
TMCL for embedded components after pre-con (Temperature Cycling Test)	77	-55°C to 125°C; 300cycles	No Failure	After 300cys	0/77
		-55°C to 125°C; 500cycles	No Failure	After 500cys	0/77
		-55°C to 125°C; 700cycles	No Failure	After 700cys	0/77
Biased-HAST after pre-con (Biased Highly Accelerated Stress Test)	77	110°C, 85%RH; 3.6V/1.95V/0.99V for 96hours.	No Failure	After 96hrs	0/77
		110°C, 85% RH; 3.6V/1.95V/0.99V for 264hours.	No Failure	After 264hrs	0/77
Un-Biased-HAST after pre-con (Un-Biased Highly Accelerated Stress Test)	77	110°C, 85%RH; 96hours.	No Failure	After 96hrs	0/77
		110°C, 85% RH; 264hours.	No Failure	After 264hrs	0/77
HTST after pre-con (High Temperature Storage Test)	45	150°C; 300hours	No Failure	After 300hrs	0/45
		150°C; 500hours	No Failure	After 500hrs	0/45

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Package Reliability Data (8D) – Full Qual

Package Qual Lot #3 (Substrate Vendor Y, EMI-Tango)

Test Items	Sample Size (ea)	Test Condition	Criteria	Intermediate read-point	Result
Pre-condition: MSL3A +4xIR	280	60° C; 60% RH; 40hours 4xIR.	No Failure	SAT result	0/280
				Test result	0/280
TMCL for embedded components after pre-con (Temperature Cycling Test)	77	-55ºC to 125ºC; 300cycles	No Failure	After 300cys	0/77
		-55ºC to 125ºC; 500cycles	No Failure	After 500cys	0/77
		-55ºC to 125ºC; 700cycles	No Failure	After 700cys	0/77
Biased-HAST after pre-con (Biased Highly Accelerated Stress Test)	77	110ºC, 85%RH; 3.6V/1.95V/0.99V for 96hours.	No Failure	After 96hrs	0/77
		110ºC, 85% RH; 3.6V/1.95V/0.99V for 264hours.	No Failure	After 264hrs	0/77
Un-Biased-HAST after pre-con (Un-Biased Highly Accelerated Stress Test)	77	110ºC, 85%RH; 96hours.	No Failure	After 96hrs	0/77
		110ºC, 85% RH; 264hours.	No Failure	After 264hrs	0/77
HTST after pre-con (High Temperature Storage Test)	45	150ºC; 300hours	No Failure	After 300hrs	0/45
		150ºC; 500hours	No Failure	After 500hrs	0/45

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MCP ESD CDM (500V, 400V, 250V) Results

BiCS5 512Gb iTLC S5E – 1D (Micro)	Sample size (ea)	Results
500V CDM	10	0F/10T
400V CDM	10	0F/10T
250V CDM	10	0F/10T
BiCS5 512Gb iTLC S5E – 2D (Micro)	**Sample size (ea)**	**Results**
500V CDM	10	0F/10T
400V CDM	10	0F/10T
250V CDM	10	0F/10T
BiCS5 512Gb iTLC S5E – 4D (Micro)	**Sample size (ea)**	**Results**
500V CDM	10	0F/10T
400V CDM	10	0F/10T
250V CDM	10	0F/10T
BiCS5 512Gb iTLC S5E – 8D (Micro)	**Sample size (ea)**	**Results**
500V CDM	10	0F/10T
400V CDM	10	0F/10T
250V CDM	10	0F/10T

- All die stacks passed ESD min. spec >= 250V.

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